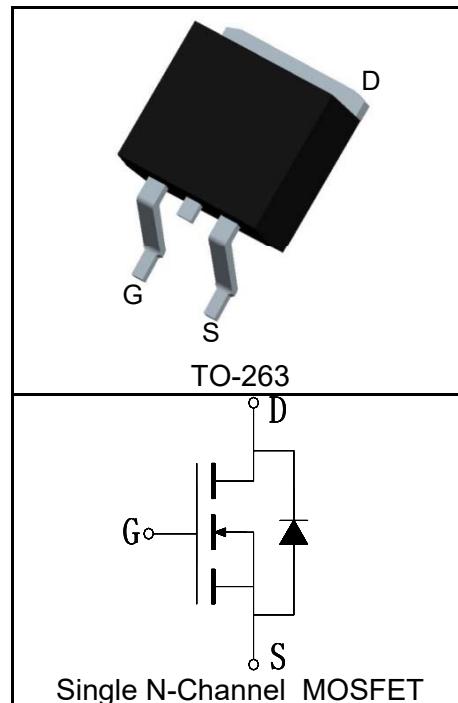


Features

- 80V/155A, $R_{DS\ (ON)} = 4.5\text{m}\Omega$ (Typ.)@ $V_{GS}=10\text{V}$
- Low $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged
- 100% Avalanche Tested

Pin Description



Applications

- Synchronous Rectification
- High efficiency DC/DC Converters
- UPS Inverter



Halogen-Free

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|--|---|-------------------------|---------------------------|
| Common Ratings ($T_C=25^\circ\text{C}$ Unless Otherwise Noted) | | | |
| V_{DSS} | Drain-Source Voltage | 80 | V |
| V_{GSS} | Gate-Source Voltage | ± 25 | |
| T_J | Maximum Junction Temperature | 175 | $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | -55 to 175 | $^\circ\text{C}$ |
| I_S | Diode Continuous Forward Current | $T_C=25^\circ\text{C}$ | 155 |
| | | | A |
| Mounted on Large Heat Sink | | | |
| $I_{DP}^{(1)}$ | 300 μs Pulse Drain Current Tested | $T_C=25^\circ\text{C}$ | 620 |
| $I_D^{(2)}$ | Continuous Drain Current($V_{GS}=10\text{V}$) | $T_C=25^\circ\text{C}$ | 155 |
| | | $T_C=100^\circ\text{C}$ | 109 |
| P_D | Maximum Power Dissipation | $T_C=25^\circ\text{C}$ | 234 |
| | | $T_C=100^\circ\text{C}$ | 117 |
| $R_{\theta JC}$ | Thermal Resistance-Junction to Case | 0.64 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}^{(3)}$ | Thermal Resistance-Junction to Ambient | 62.5 | $^\circ\text{C}/\text{W}$ |
| Drain-Source Avalanche Ratings | | | |
| $E_{AS}^{(4)}$ | Avalanche Energy, Single Pulsed | 556 | mJ |

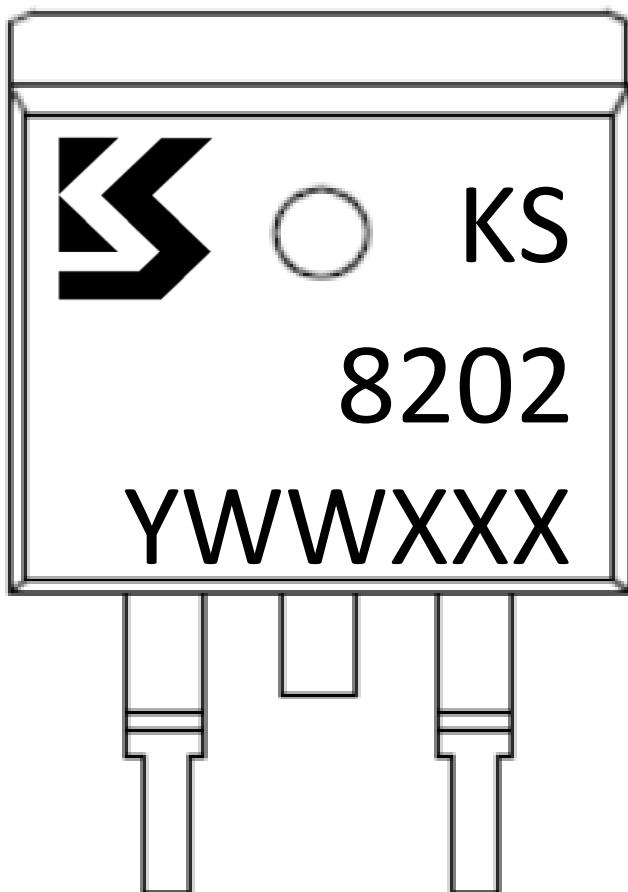
Electrical Characteristics (T_C=25°C Unless Otherwise Noted)

| Symbol | Parameter | Test Condition | KS8202GC | | | Unit |
|--|----------------------------------|--|----------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Static Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _{DS} =250μA | 80 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =80V, V _{GS} =0V | | | 1 | μA |
| | | T _J =125°C | | | 100 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _{DS} =250μA | 2 | | 4 | V |
| I _{GSS} | Gate Leakage Current | V _{GS} =±25V, V _{DS} =0V | | | ±100 | nA |
| R _{DS(ON)} ^⑤ | Drain-Source On-state Resistance | V _{GS} =10V, I _{DS} =40A | | 4.5 | 6 | mΩ |
| Diode Characteristics | | | | | | |
| V _{SD} ^⑤ | Diode Forward Voltage | I _{SD} =40A, V _{GS} =0V | | 0.85 | 1.2 | V |
| t _{rr} | Reverse Recovery Time | I _{SD} =40A, dI _{SD} /dt=100A/μs | | 28 | | ns |
| Q _{rr} | Reverse Recovery Charge | | | 110 | | nC |
| Dynamic Characteristics^⑥ | | | | | | |
| R _G | Gate Resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | | 2.6 | | Ω |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =40V, Frequency=1.0MHz | | 4115 | | pF |
| C _{oss} | Output Capacitance | | | 570 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 395 | | |
| t _{d(ON)} | Turn-on Delay Time | V _{DD} =40V, I _{DS} =40A, V _{GEN} =10V, R _G =3Ω | | 28 | | ns |
| t _r | Turn-on Rise Time | | | 66 | | |
| t _{d(OFF)} | Turn-off Delay Time | | | 87 | | |
| t _f | Turn-off Fall Time | | | 43 | | |
| Gate Charge Characteristics^⑥ | | | | | | |
| Q _g | Total Gate Charge | V _{DS} =40V, V _{GS} =10V, I _{DS} =40A | | 69 | | nC |
| Q _{gs} | Gate-Source Charge | | | 23 | | |
| Q _{gd} | Gate-Drain Charge | | | 22 | | |

- Notes:
- ①Pulse width limited by safe operating area.
 - ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
 - ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
 - ④Limited by T_{Jmax}, I_{AS}=37A, L=0.5mH, V_{DD}=48V, R_G=25Ω, Starting TJ=25°C.
 - ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
 - ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

| Device | Package | Packaging | Quantity | Reel Size | Tape width |
|----------|---------|-----------|----------|-----------|------------|
| KS8202GC | TO-263 | Tape&Reel | 800 | 13" | 24mm |

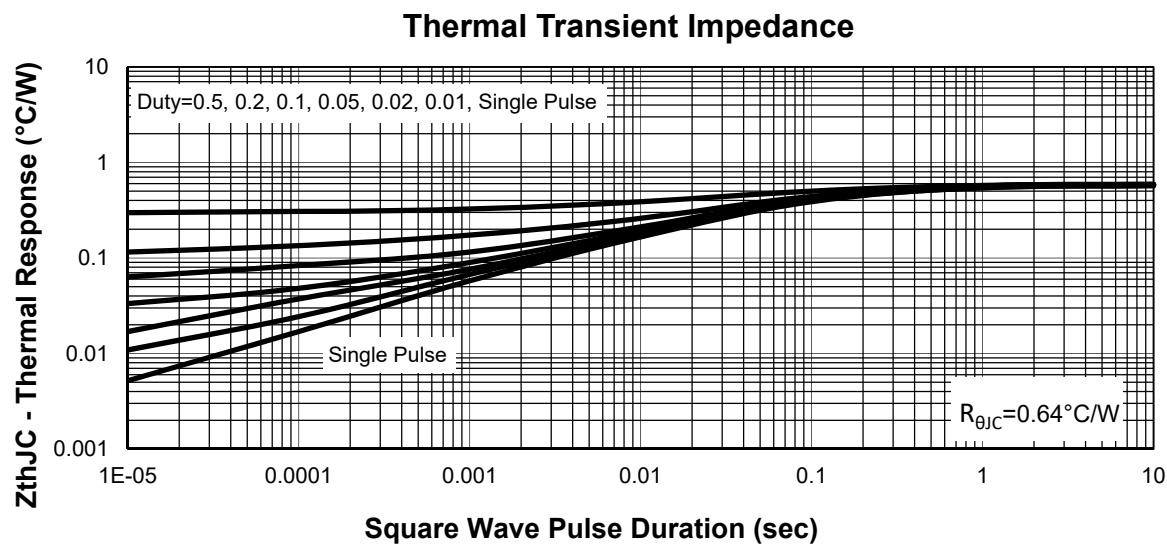
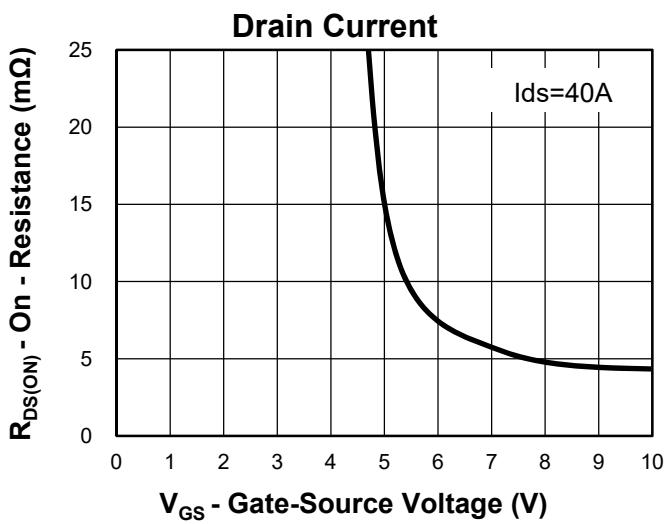
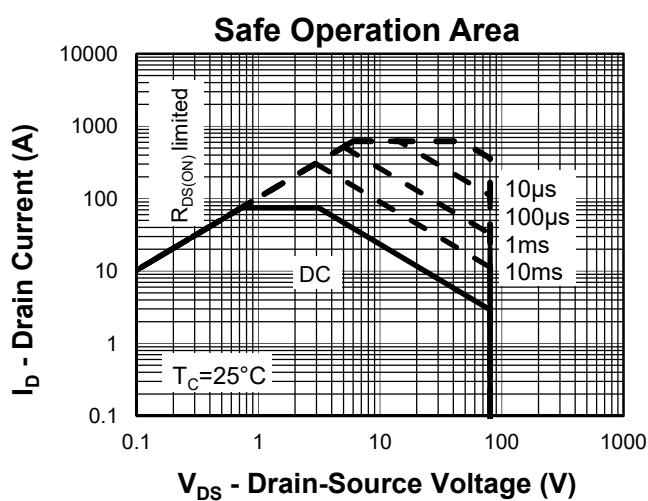
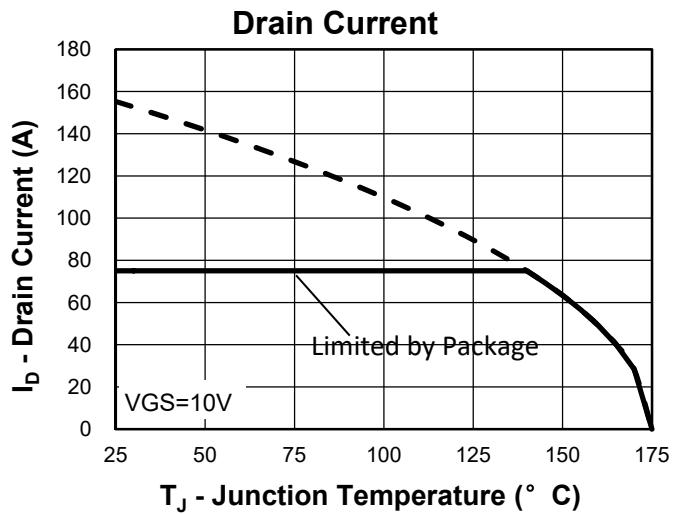
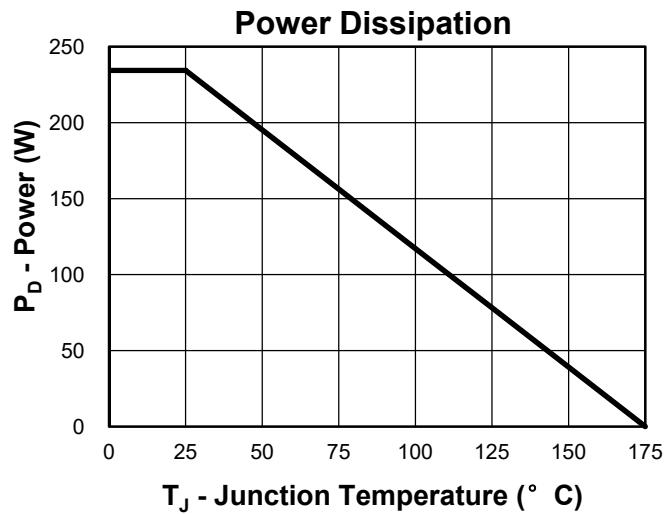


Y =Year,2017-A,2018-B,etc.

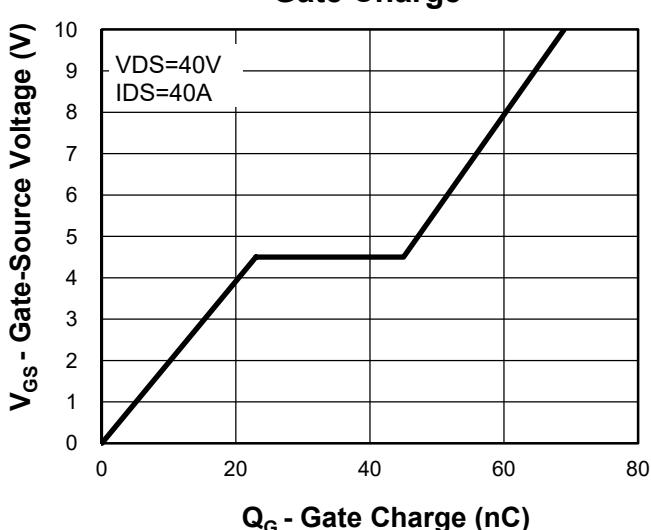
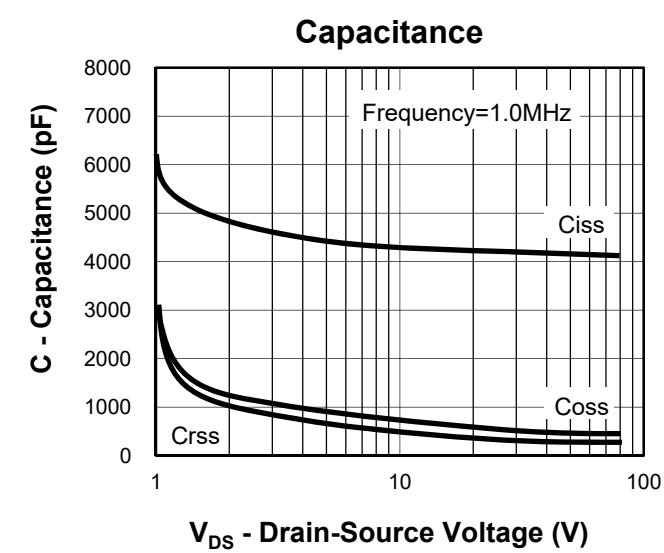
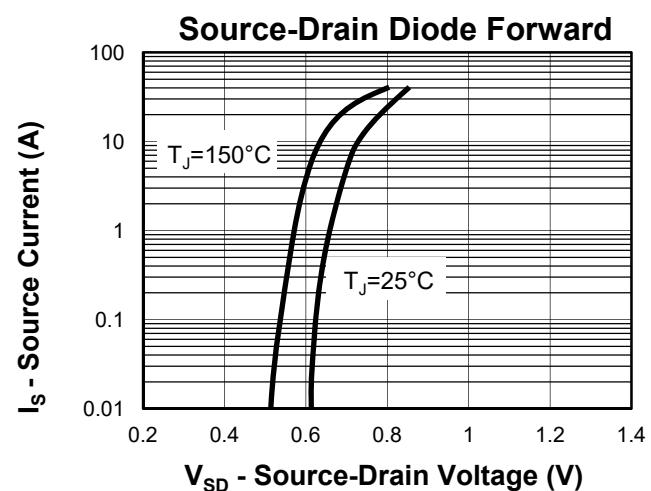
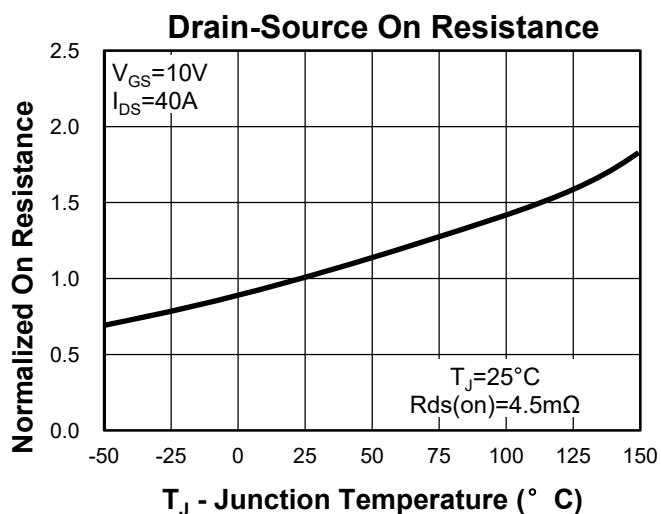
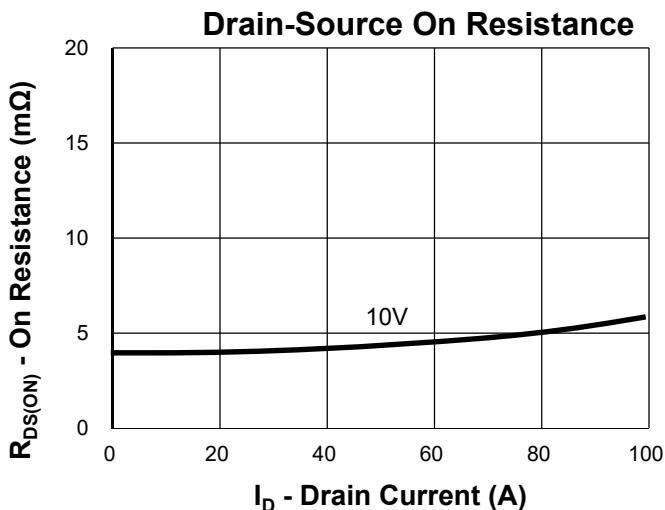
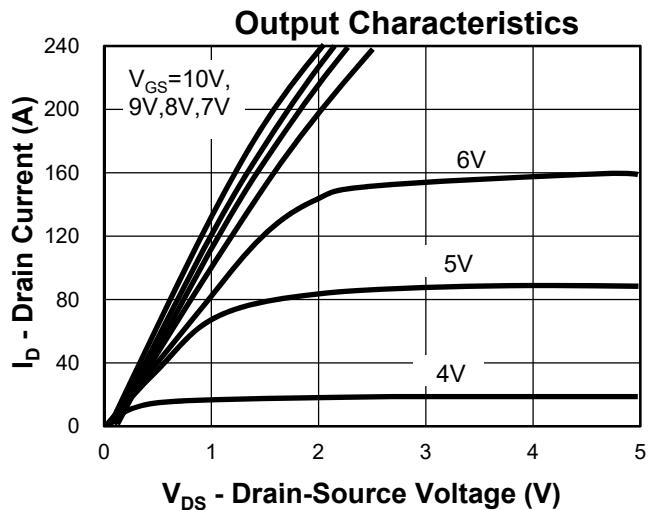
WW =Week.

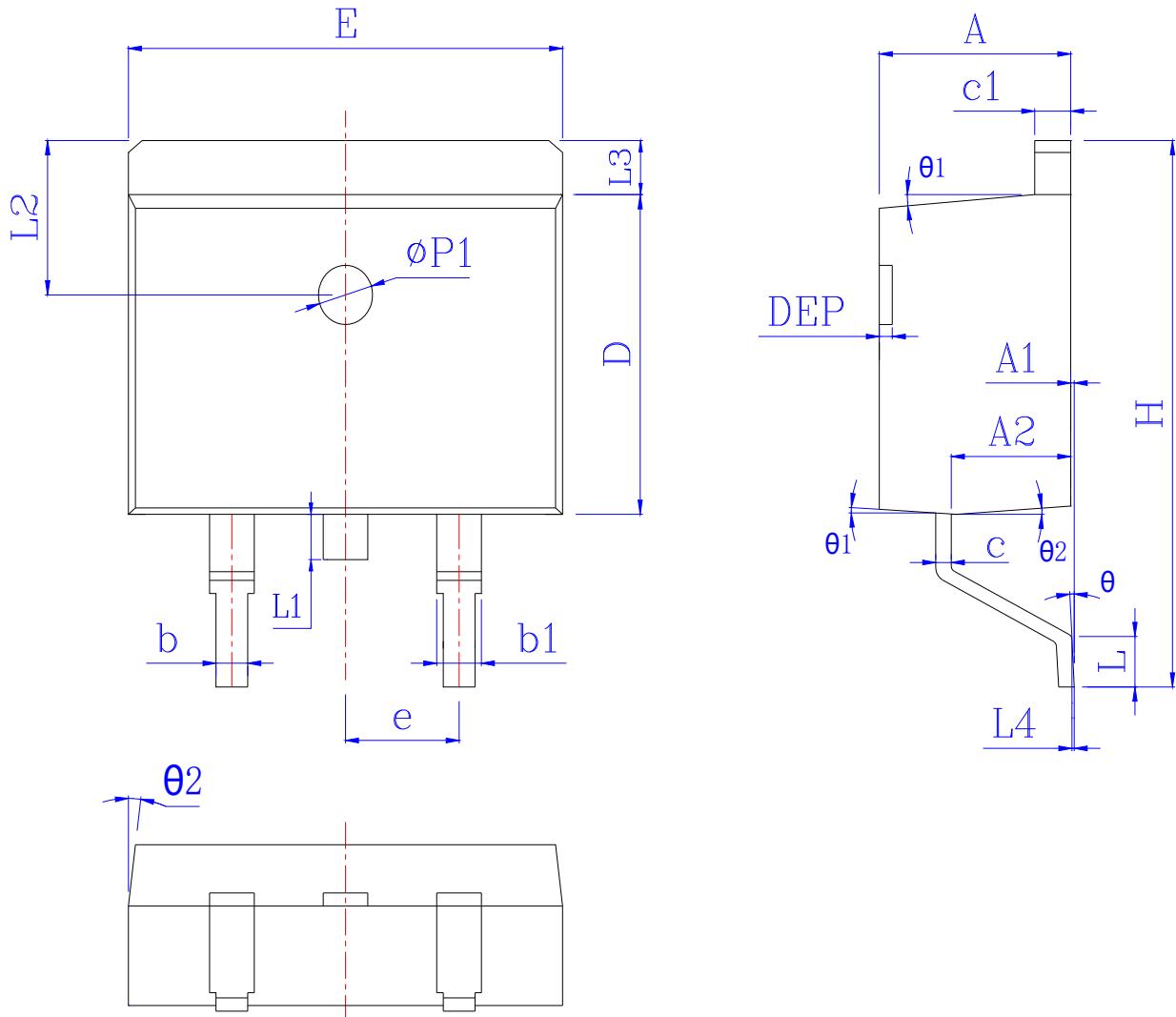
XXX =Lot number.

Typical Characteristics



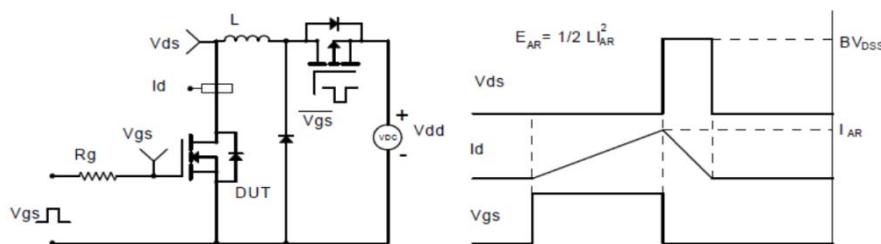
Typical Characteristics



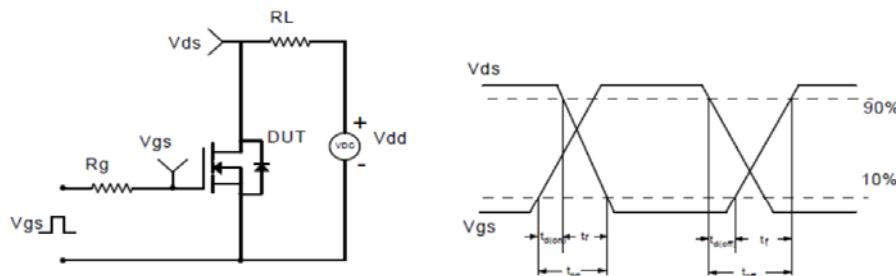
Package Information
TO-263


| SYMBOL | MM | | | INCH | | | SYMBOL | MM | | | INCH | | |
|--------|---------|-------|-------|----------|-------|-------|--------|----------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX | | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 4.40 | 4.55 | 4.72 | 0.173 | 0.179 | 0.186 | L | 1.94 | 2.30 | 2.60 | 0.076 | 0.091 | 0.102 |
| A1 | 0.00 | 0.10 | 0.25 | 0.000 | 0.005 | 0.010 | L3 | 1.17 | 1.29 | 1.40 | 0.046 | 0.051 | 0.055 |
| A2 | 2.59 | 2.69 | 2.79 | 0.102 | 0.106 | 0.110 | L1 | * | * | 1.70 | * | * | 0.067 |
| b | 0.76 | * | 0.90 | 0.030 | * | 0.035 | L4 | 0.25 BSC | | | 0.01 BSC | | |
| b1 | 1.22 | * | 1.36 | 0.048 | * | 0.054 | L2 | 2.50 REF | | | 0.098 REF | | |
| c | 0.33 | * | 0.47 | 0.013 | * | 0.019 | θ | 0° | * | 8° | 0° | * | 8° |
| c1 | 1.22 | * | 1.32 | 0.048 | * | 0.052 | θ1 | 5° | 7° | 9° | 5° | 7° | 9° |
| D | 8.60 | * | 9.29 | 0.339 | * | 0.366 | θ2 | 1° | 3° | 5° | 1° | 3° | 5° |
| E | 9.95 | * | 10.26 | 0.392 | * | 0.404 | DEP | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| e | 2.54BSC | | | 0.100BSC | | | Φp1 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 |
| H | 14.70 | 15.10 | 15.79 | 0.579 | 0.594 | 0.622 | | | | | | | |

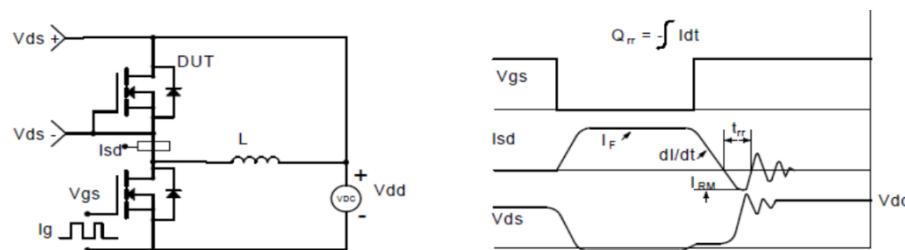
Avalanche Test Circuit and Waveforms



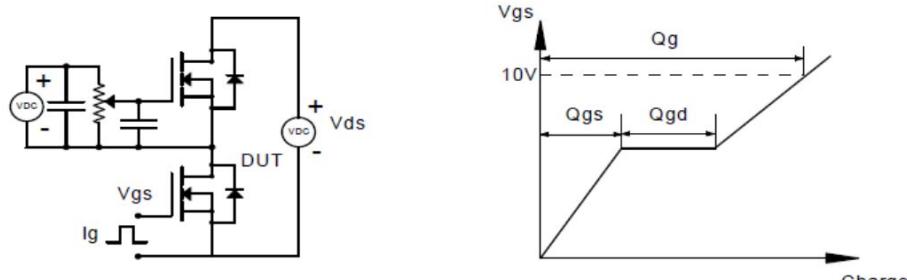
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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